

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1	("6221752").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/02/08 09:03
S2	6986	((438/612,688,742,702) or (257/459,786)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/12/07 09:12
S3	1707	S2 and ("conductive strip" or coil or "metal layer")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/26 09:46
S4	146	S3 and "contact pads"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/26 09:46
S5	63	S4 and "passivation layer"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/26 09:46
S6	2	S2 and (coil with "contact pads")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/26 16:15
S7	24	S2 and metallization adj level	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/12/07 10:35
S8	67	S2 and metal adj level	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/12/07 10:26
S9	52	S2 and "metal portion"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/12/07 10:26
S10	2	S2 and ("conductive strip" same "contact pads")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/24 16:01

S11	918	metallization adj level	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/24 15:52
S12	1	S11 and ("conductive strip" same "contact pads")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/12/07 10:35
S13	2	S11 and (coil same "contact pads")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/12/07 10:36
S14	7400	metallization adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/24 15:52
S15	501	S14 and ("conductive strip" or coil)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/24 15:53
S16	74	S15 and "passivation layer"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/24 15:59
S17	30	S16 and "contact pad"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/24 15:54
S18	58	"metal conductive strip"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/26 09:23
S23	10031	((438/677,678,669,679,680,688,945, 942,974,976) or (257/773,774)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/26 09:45
S24	2889	S23 and ("conductive strip" or coil or "metal layer")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/26 09:46

S25	370	S24 and "passivation layer"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/26 09:59
S26	3	S25 and "metal contact pads"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/26 10:19
S27	15	S23 and "metal contact pads"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/26 11:07
S28	242	S25 and @pd<"20030301"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/26 10:00
S29	0	S25 and "metal conductive pads"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/26 10:19
S30	28	"metal conductive pads"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/26 10:19
S31	20	("4770965" "4780846" "4811073" "5023701" "5182620" "5306952" "5308415" "5319206" "5320927" "5381014" "5389558" "5466956" "5516712" "5518805" "5557534"). PN. OR ("5693567").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/26 10:21
S32	11	("5055907" "5106461" "5212403" "5372967" "5501006" "5576680" "5635767" "5686764" "5884990" "6008102").PN. OR ("6515369"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/26 10:23
S33	4202	S23 and "integrated circuit"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/01/26 10:40
S34	26	S33 and "conductive strips"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/01/26 10:42

S35	210	S33 and coil	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/01/26 12:31
S36	103	S35 and "metal layer"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/01/26 12:30
S37	408902	(("438") or ("257")).CLAS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/26 10:50
S38	1251	S37 and "metallization level"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/01/26 11:01
S39	17	S38 and "conductive strip"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/01/26 10:53
S40	128	S38 and "contact pad"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/01/26 10:53
S41	7646	S37 and "metallization layer"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/01/26 11:01
S42	312	S37 and multiple with "metallization layer"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/01/26 11:01
S43	198	S42 and @pd<"20030301"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/01/26 11:04
S44	5	S43 and coil	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/01/26 11:05

S45	11	S24 and "metal contact pads"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/26 11:15
S46	103068	"metal layer"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/26 11:22
S47	535	S46 and "conductive strip"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/26 11:16
S48	29	S47 and "contact pad"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/26 11:19
S49	10	S48 and "passivation layer"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/26 12:39
S50	1439	multiple with "metal layer"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/26 11:22
S51	119	S50 and ("conductive strip" or coil)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/27 08:52
S52	1753	S33 and "metal layer"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/01/26 12:31
S53	103	S52 and coil	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/01/26 12:31
S54	2500	S46 and ("passivation layer" same etching)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/26 12:39

S55	2909	S46 and (("insulative layer" or "passivation layer") same etching)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/26 12:40
S56	159	S55 and ("conductive strip" or coil)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/26 12:40
S57	103068	"metal layer"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/26 15:43
S58	535	S57 and "conductive strip"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/26 15:43
S59	29	S58 and "contact pad"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/26 16:16
S60	15	S59 and aluminum	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/01/26 15:45
S61	170	"contact pad" adj2 aluminum	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/01/26 15:46
S62	124	S61 and "integrated circuit"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/01/26 15:46
S63	7048	((438/612,688,742,702) or (257/459,786)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/26 16:15
S66	258	S58 and ("integrated circuit" or IC)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/01/26 16:22

S67	14	S66 and "contact pad"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/26 16:17
S68	0	S66 and "metal coil"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/01/26 16:22
S69	65	S66 and "coil"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/01/26 16:22
S70	30	("5206712" "5387888" "5559363" "5654681" "5783976").PN. OR ("5929510").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/26 16:42
S71	408902	(("438") or ("257")).CLAS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/27 08:53
S72	7646	S71 and "metallization layer"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/01/27 08:53
S73	412	S72 and ("conductive strip" or coil)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/27 09:07
S74	88445	("integrated circuit"or ic) same ("conductive strip" or coil)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/27 09:08
S75	889246	("integrated circuit"or ic)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/27 09:21
S76	86123	S74 and @pd<"20030301"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/27 09:09

S77	168	S76 and "metal layer"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/27 09:16
S78	98	S76 and "contact pad"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/27 09:16
S79	164	S73 and ("integrated circuit"or ic)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/27 09:41
S80	1542	forming with ic with (contact pads same coils)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/27 10:18
S81	1277	S80 and @pd<"20030301"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/27 09:48
S82	47454	ic with (contact pads same coils)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/27 10:18
S83	3428850	(contact pads same coils)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/27 10:18
S84	207	("contact pads" same coils)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/27 10:18
S85	1456	(257/528,531,904).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/27 11:38
S86	653	S85 and ("conductive strip" or coil or inductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/01/27 11:45

S87	252	S86 and ("metal layer" or "contact pad")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/01/27 12:57
S88	1	("6221752").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/27 12:55
S89	10	("4442966" "5300461" "5380401" "5384284" "5451291" "5519254" "5747868" "5770100" "5882489").PN. OR ("6221752").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/27 12:56
S90	30	S86 and ("bond pad")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/01/27 12:58
S91	5	("5450263" "5539241" "5825092" "6211056").PN. OR ("6437418").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/27 13:15
S92	1456	(257/528,531,904).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/01/30 11:26
S93	653	S92 and ("conductive strip" or coil or inductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/01/30 11:26
S94	120	S93 and reliability	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/01/30 11:26
S95	52	S94 and ("metal layer" or "contact pad" or "bond pad")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/08 11:47
S96	11	(("20010032981") or ("6939808") or ("6407004") or ("6395637") or ("6383945") or ("6184140") or ("6025268") or ("5970379") or ("5858257") or ("5270254") or ("4067100")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/02/08 09:05

S97	8745	(438/597,598,599,612,669,671,672, 673,674,675,688,720,721,722,734, 742,754).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/02/08 09:18
S98	1	S97 and ((etch\$3 or reduc\$3) near10 thick\$3 near10 (metal or conduct\$3) near10 overetch\$3 near10 (metal or Al))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/08 09:20
S99	191	S97 and ((etch\$3 or reduc\$3) near10 thick\$3 near10 (metal or conduct\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/08 11:05
S100	13	S99 and (overetch\$3 near10 (metal or Al))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/08 09:21
S101	0	("2004/0157438").URPN.	USPAT	OR	ON	2006/02/08 10:34
S102	16	("4370173" "4871422" "5700383" "5709755" "5714203" "5794299" "5806126" "5810938" "5858109" "5868863" "5935871" "6096652" "6207559").PN. OR ("6610601"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/08 10:40
S103	3	S97 and ((etch\$3 or reduc\$3 or cmp) near10 thick\$3 near10 thin near10 (metal or conduct\$3) near10 (pad or contact or electrode))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/08 11:08
S104	108	((etch\$3 or reduc\$3 or cmp) near10 thick\$3 near10 thin near10 (metal or conduct\$3) near10 (pad or contact or electrode))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/08 11:11
S105	12605	((etch\$3 or reduc\$3 or cmp) same thick\$3 same thin same (metal or conduct\$3) same (pad or contact or electrode))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/08 11:12
S106	3102	S105 and ((protection or passivation or insulat\$3) adj layer)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/08 11:13

S10 7	399612	((etch\$3 or reduc\$3 or cmp) same (metal or conduct\$3) same (pad or contact or electrode))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/08 11:16
S10 8	61086	S107 and ((protection or passivation or insulat\$3) adj layer)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/08 11:16
S10 9	1345	S108 and "over etch"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/08 11:16
S11 0	1212	S109 and (al or aluminum)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/08 11:16
S11 1	139864	((etch or reduce or cmp) same (metal or conductive) same (pad or contact or electrode))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/08 11:16
S11 2	22363	S111 and ((protection or passivation or insulating) adj layer)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/08 11:16
S11 3	926	S112 and "over etch"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/08 11:16
S11 4	1212	S110 and (al or aluminum)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/08 11:17
S11 5	840	S113 and (al or aluminum)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/08 11:42
S11 6	10052	wire near15 ("contact pad" or "bond pad")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/08 11:49

S11 7	2219	S116 and etch	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/08 11:48
S11 8	2018	S117 and (al or aluminum)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/08 11:48
S11 9	8	wire near15 ("contact pad" or "bond pad") near15 etch same (al or aluminum)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/08 12:44
S12 0	0	("2003/0119297").URPN.	USPAT	OR	ON	2006/02/08 12:01
S12 1	0	("2002/0025585").URPN.	USPAT	OR	ON	2006/02/08 12:41
S12 2	136	wire same ("contact pad" or "bond pad") same etch same (al or aluminum)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/08 14:06
S12 3	16	("4463059" "5249728" "5455387" "5476815" "5554940" "5719449" "5774340" "5844168" "5969424" "5977624" "6181569" "6232147" "6232666" "6344401" "6420787" "6577008").PN. OR ("6762117"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/08 14:06
S12 4	2571	(438/688,720,721,722,734,742,754). CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2006/02/08 14:06
S12 5	4	S124 and (wire same ("contact pad" or "bond pad") same etch same (al or aluminum))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/08 14:07